

PALM INTRANET

Day: Monday Date: 4/19/2004 Time: 12:50:48

Inventor Name Search Result

Your Search was:

Last Name = LEE

First Name = KUN-TACK

Application#	Patent#	Status	Date Filed	Title	Inventor Name 14
10728517	Not Issued	030	12/05/2003	CLEANING SOLUTION AND METHOD FOR SELECTIVELY REMOVING LAYER IN A SILICIDATION PROCESS	LEE, KUN-TACK
<u>10727962</u>	Not Issued	020	12/04/2003	CLEANING SOLUTION FOR REMOVING DAMAGED PORTION OF FERROELECTRIC LAYER AND CLEANING METHOD USING THE SAME	LEE, KUN-TACK
<u>10441070</u>	Not Issued	041	05/20/2003	METHOD OF FORMING METAL INTERCONNECTION USING PLATING AND SEMICONDUCTOR DEVICE MANUFACTURED BY THE METHOD	LEE, KUN-TACK
10434052	Not Issued	041	05/08/2003	METHOD OF MANUFACTURING STORAGE NODES OF A SEMICONDUCTOR MEMORY DEVICE USING A TWO-STEP ETCHING PROCESS	LEE, KUN-TACK
10357098	Not Issued	030	02/03/2003	APPARATUS AND METHODS FOR CLEANING SEMICONDUCTOR WAFERS USING VAPORIZED CHEMICALS	LEE, KUN-TACK
<u>10135452</u>	Not Issued	061	05/01/2002	METHOD OF AND SYSTEM FOR CLEANING A SEMICONDUCTOR WAFER SIMULTANEOUSLY USING ELECTROLYTICALLY IONIZED WATER AND DILUTED HYDROFLUORIC ACID	LEE, KUN-TACK

10017415	Not Issued	071	12/18/2001	SINGLE TYPE OF	LEE, KUN-TACK
10017413	TVOC ISSUED	V/1	12.10,200	SEMICONDUCTOR WAFER CLEANING APPARATUS AND METHOD OF USING THE SAME	
<u>10012564</u>	6701942	150	12/12/2001	METHOD OF AND APPARATUS FOR REMOVING CONTAMINANTS FROM SURFACE OF A SUBSTRATE	LEE, KUN-TACK
09945722	6565736	150	09/05/2001	WET PROCESS FOR SEMICONDUCTOR DEVICE FABRICATION USING ANODE WATER CONTAINING OXIDATIVE SUBSTANCES AND CATHODE WATER CONTAINING REDUCTIVE SUBSTANCES, AND ANODE WATER AND CATHODE WATER USED IN THE WET PROCESS	LEE, KUN-TACK
09899226	6712078	150	07/06/2001	APPARATUS FOR CLEANING SEMICONDUCTOR WAFER AND METHOD FOR CLEANING WAFER USING THE SAME	LEE, KUN-TACK
<u>09797454</u>	Not Issued	083	03/01/2001	CLEANING SOLUTION FOR REMOVING DAMAGED PORTION OF FERROELECTRIC LAYER AND CLEANING METHOD USING THE SAME	LEE, KUN-TACK
09689814	Not Issued	041	10/13/2000	METHOD OF REMOVING OXIDE LAYER AND SEMICONDUCTOR MANUFACTURING APPARATUS FOR REMOVING OXIDE LAYER	LEE, KUN-TACK
09662120	6610596	150	09/14/2000	METHOD OF FORMING METAL INTERCONNECTION USING PLATING AND SEMICONDUCTOR DEVICE MANUFACTURED BY THE METHOD	LEE, KUN-TACK
09451844	6399552	150	12/01/1999		LEE , KUN-TACK

	Trust Litting	11100110	
•	Last Name	First Name	
Inventor Search C	ompleted: No	o Records to Display.	
		CLEANING METHOD USING THE SAME	
₩		OF CIRCUIT SUBSTRATE	

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Search Results - Record(s) 1 through 9 of 9 returned.

1. Document ID: US 20020197944 A1

Using default format because multiple data bases are involved.

L5: Entry 1 of 9

File: PGPB

Dec 26, 2002

PGPUB-DOCUMENT-NUMBER: 20020197944

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020197944 A1

TITLE: Method and apparatus for cleaning polishing surface of polisher

PUBLICATION-DATE: December 26, 2002

INVENTOR-INFORMATION:

NAME

CITY

STATE

COUNTRY RULE-47

Inoue, Tatsuo

Kanagawa-ken

JΡ

Komatsu, Mitsunori

Kanagawa-ken

JP

US-CL-CURRENT: 451/444

2. Document ID: US 20020108641 A1

L5: Entry 2 of 9

File: PGPB

Aug 15, 2002

PGPUB-DOCUMENT-NUMBER: 20020108641

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020108641 A1

TITLE: Single type of semiconductor wafer cleaning apparatus and method of using

the same

PUBLICATION-DATE: August 15, 2002

INVENTOR-INFORMATION:

NAME

CITY

STATE

COUNTRY

RULE-47

Lee, Kun-Tack

Suwon-city

KR

Han, Yong-Pil

Seoul

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Hah, Sang-Rok

Seoul

KR

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US-CL-CURRENT: $\underline{134/30}$; $\underline{134/102.1}$, $\underline{134/153}$, $\underline{134/33}$, $\underline{134/36}$, $\underline{134/902}$, $\underline{134/95.2}$,

134/95.3

ABSTRACT:

A semiconductor wafer <u>cleaning apparatus</u> includes a <u>gas spraying</u> unit, having a gas injection tube and a gas guard extending therearound, for spraying cleaning gas into a water layer formed on a wafer. The gas guard forms a small chamber just above the water layer, so that the partial pressure of gas injected from the gas injection tube is increased in the small chamber, whereupon the cleaning gas readily dissolves in the water layer. As a result, a cleaning solution having a high concentration of cleaning gas is produced, whereby the cleaning efficacy of the solution is high. Subsequently, a drying gas, such as isopropyl alcohol, for drying the wafer can be ejected onto the water layer using the <u>gas spraying</u> unit. Thus, the semiconductor wafer <u>cleaning apparatus</u> has a simple structure.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	-Attachments	Claims	KOME	Drawe De

3. Document ID: US 20010021625 A1

L5: Entry 3 of 9

File: PGPB

Sep 13, 2001

PGPUB-DOCUMENT-NUMBER: 20010021625

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20010021625 A1

TITLE: Method and apparatus for cleaning polishing surface of polisher

PUBLICATION-DATE: September 13, 2001

INVENTOR-INFORMATION:

NAME

CITY

STATE

COUNTRY RULE-47

Inoue, Tatsuo

Kanagawa-ken

JΡ

Komatsu, Mitsunori

Kanagawa-ken

JP

US-CL-CURRENT: 451/56

ABSTRACT:

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A polishing surface cleaning method and apparatus are capable of effectively removing the polishing residue from the polishing surface of a polishing table in a polisher by using a minimal amount of cleaning liquid. In the polisher, a workpiece to be polished is pressed against the polishing surface of the polishing table to polish the workpiece by relative motion between the polishing surface and the workpiece. The polishing surface cleaning apparatus uses mixing spray nozzles for mixing together a cleaning liquid and a gas and spraying the resulting fluid mixture on the polishing surface to clean it.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	'Claims	Kowic Drawi De

4. Document ID: US 6610168 B1

L5: Entry 4 of 9

File: USPT

Aug 26, 2003

US-PAT-NO: 6610168

DOCUMENT-IDENTIFIER: US 6610168 B1

** See image for Certificate of Correction **

TITLE: Resist film removal apparatus and resist film removal method

DATE-ISSUED: August 26, 2003

INVENTOR-INFORMATION:

NAME

CITY

STATE

ZIP CODE

COUNTRY

Miki; Nobuhiro

Tokyo

511 0052

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Nitta; Takahisa

Tokyo

JP

US-CL-CURRENT: $\underline{156}/\underline{344}$; $\underline{134}/\underline{26}$, $\underline{134}/\underline{30}$, $\underline{134}/\underline{39}$, $\underline{430}/\underline{256}$, $\underline{430}/\underline{260}$

ABSTRACT:

A line slit nozzle for spraying steam is disposed along a diameter of a resist film. Steam containing a mist is sprayed onto a surface of the resist film. The film is thereby peeled off and removed. By using a change in physical properties (swelling, etc.) of the resist film by water, the film is easily and surely peeled off. Breakaway from much resources/energy consumption type techniques is realized. In other words, realized are environment-symbiosis type techniques by which resist films can be removed independently of the quantity of energy and kinds of chemical solvents.

3 Claims, 10 Drawing figures Exemplary Claim Number: 1 Number of Drawing Sheets: 7

Full Til	le Citation	Front	Review	Classification	Date	Reference	Claims KWC Draw
-		,					

5. Document ID: US 6598805 B2

L5: Entry 5 of 9

File: USPT

Jul 29, 2003

US-PAT-NO: 6598805

DOCUMENT-IDENTIFIER: US 6598805 B2

TITLE: Substrate cleaning apparatus

DATE-ISSUED: July 29, 2003

INVENTOR-INFORMATION:

NAME

CITY

STATE

ZIP CODE

COUNTRY

Sakai; Takamasa

Kyoto

JP

Hirae; Sadao

Kyoto

JΡ

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US-CL-CURRENT: <u>239/128</u>; <u>134/22.15</u>, <u>134/30</u>, <u>134/36</u>, <u>134/902</u>, <u>239/132</u>, <u>239/136</u>, <u>239/137</u>, <u>239/139</u>, <u>239/419</u>

ABSTRACT:

A gas mixture of dry steam and nitrogen gas serving as carrier gas is blown into a hot water mist injection port for rendering the nitrogen gas serve as a medium absorbing latent heat of condensation, thereby smoothly progressing condensation of water vapor and efficiently forming hot water mist. The water vapor is condensed in the hot water mist injection port formed by a cylindrical pipe for supplying latent heat of condensation to the nitrogen gas and dilating the same, thereby accelerating the flow of the hot water mist and spraying the hot water mist to a substrate from the hot water mist injection port at a high speed. Small droplets contained in the high-speed hot water mist have high kinetic energy and high thermal energy, for exhibiting a large colliding effect and a high activation effect with respect to small contaminants adhering to the substrate. A substrate cleaning apparatus capable of spraying hot water mist attaining a high cleaning effect to a substrate is provided.

11 Claims, 3 Drawing figures Exemplary Claim Number: 1 Number of Drawing Sheets: 3

Full	Title	Citation	Front	Classification	Reference	Claims KWC Draw
			'	 	 	

6. Document ID: US 6443816 B2

L5: Entry 6 of 9

File: USPT

Sep 3, 2002

US-PAT-NO: 6443816

DOCUMENT-IDENTIFIER: US 6443816 B2

TITLE: Method and apparatus for 'cleaning polishing surface of polisher

DATE-ISSUED: September 3, 2002

INVENTOR-INFORMATION:

NAME CITY STATE ZIP CODE COUNTRY

Inoue; Tatsuo kanagawa-ken JP

Komatsu; Mitsunori kanagawa-ken JP

US-CL-CURRENT: 451/56; 451/444, 451/72

ABSTRACT:

h

A polishing surface cleaning method and apparatus are capable of effectively removing the polishing residue from the polishing surface of a polishing table in a polisher by using a minimal amount of cleaning liquid. In the polisher, a workpiece to be polished is pressed against the polishing surface of the polishing table to polish the workpiece by relative motion between the polishing surface and the workpiece. The polishing surface cleaning apparatus uses mixing spray nozzles for mixing together a cleaning liquid and a gas and spraying the resulting fluid mixture on the polishing surface to clean it.

9 Claims, 10 Drawing figures Exemplary Claim Number: 1 Number of Drawing Sheets: 5

Full Title Citation Front Review Classification Date Reference Claims NMC Draw. De

7. Document ID: US 5012980 A

L5: Entry 7 of 9

File: USPT

May 7, 1991

US-PAT-NO: 5012980

DOCUMENT-IDENTIFIER: US 5012980 A

TITLE: Linear-spraying device

DATE-ISSUED: May 7, 1991

INVENTOR-INFORMATION:

CITY STATE ZIP CODE COUNTRY NAME FR Viannay; Stephane G. J. Voisin-le-Bretonneux FR Boulogne-Billancourt Roth; Bernard M. FR Mirigay; Solange M. V. Chaville FR Chastang; Georges J. B. Coignieres

US-CL-CURRENT: 239/423; 239/543, 239/568

ABSTRACT:

The pressurized gas is supplied by two sleeves separated by a sprayer device forming a funnel. The narrow end of the funnel has a spraying head with, in the plane of symmetry (P) of the device, at least one slot through which the liquid flows. The pressurized gas passes through a series of openings provided on either side of the slot. A liquid supply tube is arranged parallel in relation to the wide end of the funnel and has openings through which the liquid flows directly or indirectly into the funnel and passes through the slot without any appreciable pressure.

9 Claims, 6 Drawing figures Exemplary Claim Number: 1 Number of Drawing Sheets: 3

Full Title Citation Front Review Classification Data Reference Claims K	MC Draw D

8. Document ID: US 4799941 A

L5: Entry 8 of 9

File: USPT

Jan 24, 1989

US-PAT-NO: 4799941

DOCUMENT-IDENTIFIER: US 4799941 A

TITLE: Method and arrangement for condensing flue gases

DATE-ISSUED: January 24, 1989

INVENTOR-INFORMATION:

NAME

CITY STATE ZIP CODE COUNTRY

Westermark; Mats O. J.

Taby

SE

US-CL-CURRENT: 95/199; 110/215, 122/7R, 261/146, 261/151, 261/153, 261/157,

261/DIG.9, 95/225, 96/266

ABSTRACT:

The invention relates to a method for condensing flue gas in combustion plants, and an arrangement of apparatus herefor. In accordance with the invention the flue gas is cooled and humidified by bringing the gas into direct contact with water, whereafter the water vapor in the gas is cooled and condensed, the heat of condensation being recovered by indirect heat exchange. The heat of condensation is transferred partially to a heat absorbing medium, preferably return water in a district heating network, and partially to a circuit in which water is circulated within the plant, this water being used for heating and humidifying the combustion air.

10 Claims, 2 Drawing figures Exemplary Claim Number: 1 Number of Drawing Sheets: 1

Full Title	Citation I	Front Review	Classification	Date Reference		Claims	KWWC Draww De
9.	Documen	t ID: US 22	04771 A			•	
TE. Poto	y 9 of 9		•	File: USO	ാറ	Jun	18, 1940

US-PAT-NO: 2204771

L5: Entry 9 of 9

DOCUMENT-IDENTIFIER: US 2204771 A

TITLE: Gas washing means

DATE-ISSUED: June 18, 1940

INVENTOR-NAME: RICE OWEN R; SCHOFIELD WILFRED C

US-CL-CURRENT: 261/22, 261/111

Full	Title Citation		Review	Classification	Date	Reference Claims KWC D
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GASES	602437
SPRAYING	310917
SPRAYINGS	566
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(L3 AND (GAS SPRAYING)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	9

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